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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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Thyristor Modules

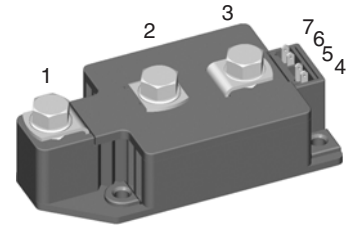
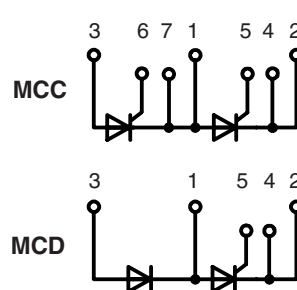
Thyristor/Diode Modules

$$I_{TRMS} = 2x 500 A$$

$$I_{TAVM} = 2x 320 A$$

$$V_{RRM} = 2200 V$$

V_{RSM}	V_{RRM}	Type	
V_{DSM}	V_{DRM}		
V	V	Version 1	Version 1
2300	2200	MCC 310-22io1	MCD 310-22io1



Symbol	Conditions	Maximum Ratings	
I_{TRMS}, I_{FRMS}	$T_{VJ} = T_{VJM}$	500	A
I_{TAVM}, I_{FAVM}	$T_C = 85^\circ C; 180^\circ$ sine	320	A
I_{TSM}, I_{FSM}	$T_{VJ} = 45^\circ C$	$t = 10$ ms (50 Hz), sine	8000 A
	$V_R = 0$	$t = 8.3$ ms (60 Hz), sine	8600 A
I^2dt	$T_{VJ} = 45^\circ C$	$t = 10$ ms (50 Hz), sine	320 000 A^2s
	$V_R = 0$	$t = 8.3$ ms (60 Hz), sine	310 000 A^2s
$(di/dt)_{cr}$	$T_{VJ} = T_{VJM}$	repetitive, $I_T = 960$ A	100 $A/\mu s$
	$f = 50$ Hz, $t_p = 200$ μs $V_D = \frac{2}{3} V_{DRM}$ $I_G = 1$ A $di_G/dt = 1$ $A/\mu s$	non repetitive, $I_T = 320$ A	500 $A/\mu s$
$(dv/dt)_{cr}$	$T_{VJ} = T_{VJM}; V_{DR} = \frac{2}{3} V_{DRM}$ $R_{GK} = \infty$; method 1 (linear voltage rise)		1000 $V/\mu s$
P_{GM}	$T_{VJ} = T_{VJM}; t_p = 30$ μs	120	W
	$I_T = I_{TAVM}; t_p = 500$ μs	60	W
P_{GAV}		20	W
V_{RGM}		10	V
T_{VJ}		-40...+140	$^\circ C$
T_{VJM}		140	$^\circ C$
T_{stg}		-40...+125	$^\circ C$
V_{ISOL}	50/60 Hz, RMS; $t = 1$ min	3000	V~
	$I_{ISOL} \leq 1$ mA; $t = 1$ s	3600	V~
M_d	Mounting torque (M5)	2.5-5/22-44	Nm/lb.in.
	Terminal connection torque (M8)	12-15/106-132	Nm/lb.in.
Weight	Typical including screws	320	g

Features

- International standard package
- Direct copper bonded Al_2O_3 -ceramic base plate
- Planar passivated chips
- Isolation voltage 3600 V~
- UL registered, E 72873
- Keyed gate/cathode twin pins

Applications

- Motor control
- Power converter
- Heat and temperature control for industrial furnaces and chemical processes
- Lighting control
- Contactless switches

Advantages

- Space and weight savings
- Simple mounting
- Improved temperature and power cycling
- Reduced protection circuits

Data according to IEC 60747 and refer to a single thyristor/diode unless otherwise stated.

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Symbol	Conditions	Characteristic Values	
I_{RRM}	$T_{VJ} = T_{VJM}; V_R = V_{RRM}; V_D = V_{DRM}$	70	mA
I_{DRM}		40	mA
V_T, V_F	$I_T, I_F = 600 \text{ A}; T_{VJ} = 25^\circ\text{C}$	1.40	V
V_{T0}	For power-loss calculations only ($T_{VJ} = 140^\circ\text{C}$)	0.8	V
r_T		0.82	m Ω
V_{GT}	$V_D = 6 \text{ V}; T_{VJ} = 25^\circ\text{C}$	2	V
	$T_{VJ} = -40^\circ\text{C}$	3	V
I_{GT}	$V_D = 6 \text{ V}; T_{VJ} = 25^\circ\text{C}$	150	mA
	$T_{VJ} = -40^\circ\text{C}$	200	mA
V_{GD}	$T_{VJ} = T_{VJM}; V_D = \frac{2}{3} V_{DRM}$	0.25	V
I_{GD}		10	mA
I_L	$T_{VJ} = 25^\circ\text{C}; t_p = 30 \mu\text{s}; V_D = 6 \text{ V}$ $I_G = 0.45 \text{ A}; di_G/dt = 0.45 \text{ A}/\mu\text{s}$	200	mA
I_H	$T_{VJ} = 25^\circ\text{C}; V_D = 6 \text{ V}; R_{GK} = \infty$	150	mA
t_{gd}	$T_{VJ} = 25^\circ\text{C}; V_D = \frac{1}{2} V_{DRM}$ $I_G = 1 \text{ A}; di_G/dt = 1 \text{ A}/\mu\text{s}$	2	μs
t_q	$T_{VJ} = T_{VJM}; I_T = 300 \text{ A}, t_p = 200 \mu\text{s}; -di/dt = 10 \text{ A}/\mu\text{s}$ $V_R = 100 \text{ V}; dv/dt = 50 \text{ V}/\mu\text{s}; V_D = \frac{2}{3} V_{DRM}$	typ. 200	μs
Q_S	$T_{VJ} = 125^\circ\text{C}; I_T, I_F = 400 \text{ A}, -di/dt = 50 \text{ A}/\mu\text{s}$	760	μC
I_{RM}		275	A
R_{thJC}	per thyristor/diode; DC current per module	0.112	K/W
R_{thJK}	per thyristor/diode; DC current per module	0.056	K/W
	other values see Fig. 8/9	0.152	K/W
		0.076	K/W
d_s	Creepage distance on surface	12.7	mm
d_A	Strike distance through air	9.6	mm
a	Maximum allowable acceleration	50	m/s ²

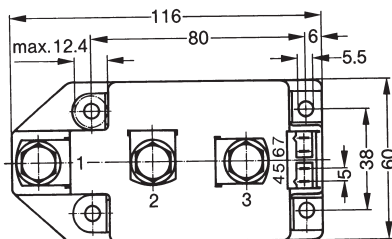
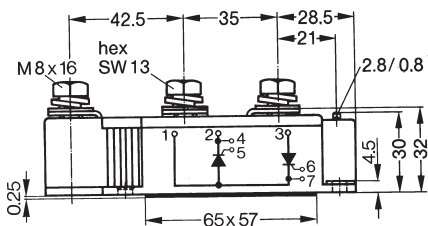
Optional accessories for modules

Keyed gate/cathode twin plugs with wire length = 350 mm, gate = yellow, cathode = red

Type ZY 180L (L = Left for pin pair 4/5) } UL 758, style 1385,
Type ZY 180R (R = right for pin pair 6/7) } CSA class 5851, guide 460-1-1

Dimensions in mm (1 mm = 0.0394")

MCC



MCD

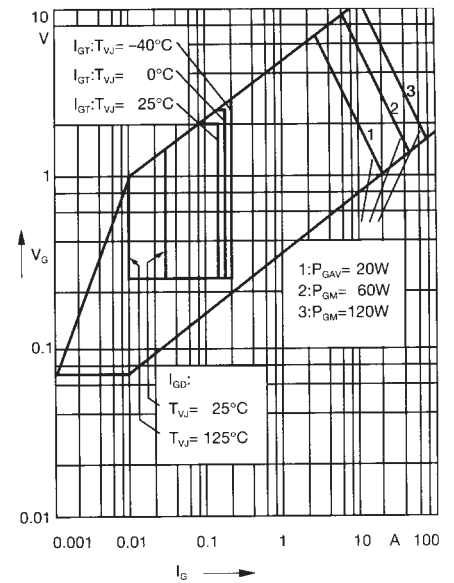
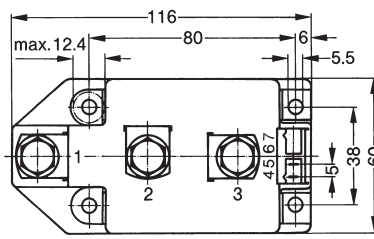
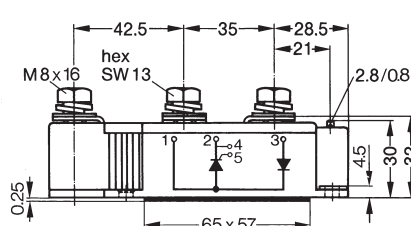


Fig. 1 Gate trigger characteristics

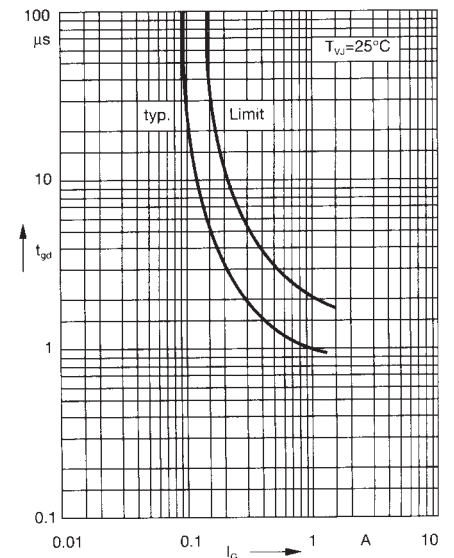
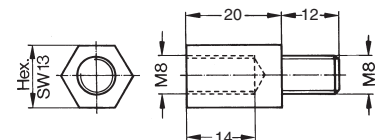


Fig. 2 Gate trigger delay time

Threaded spacer for higher Anode/Cathode construction:
Type ZY 250, material brass



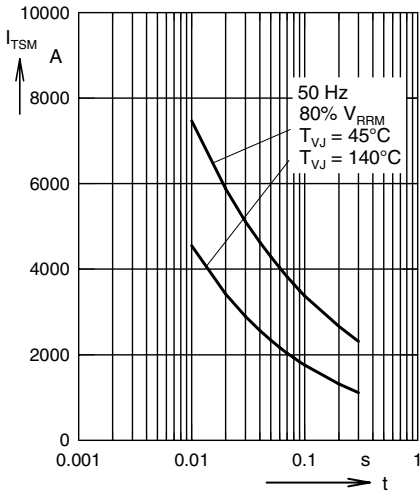


Fig. 3 Surge overload current
 I_{TSM} , I_{FSM} : Crest value, t : duration

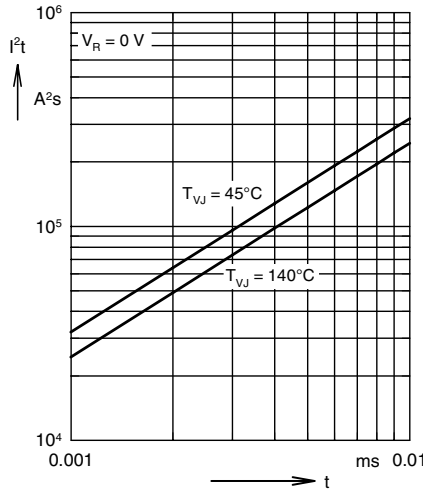


Fig. 4 $\int i^2 dt$ versus time (1-10 ms)

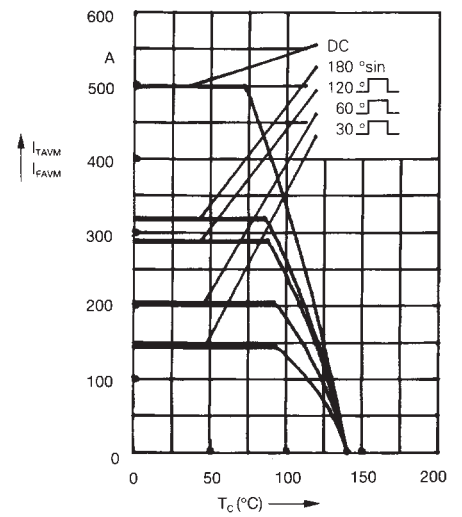


Fig. 4a Maximum forward current at case temperature

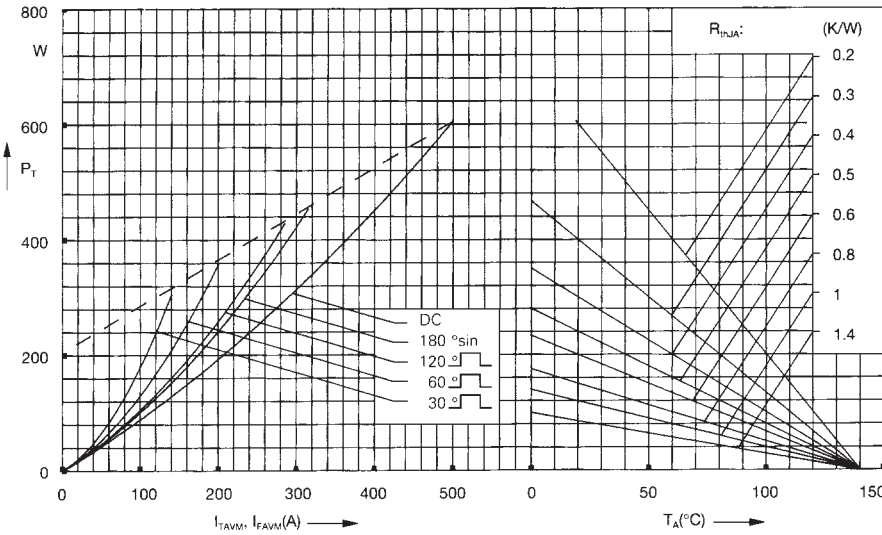


Fig. 5 Power dissipation versus on-state current and ambient temperature (per thyristor or diode)

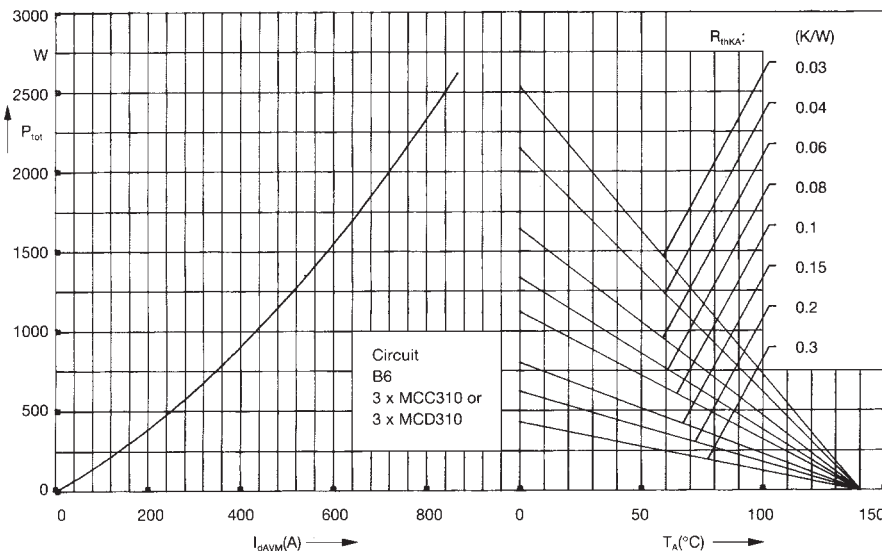


Fig. 6 Three phase rectifier bridge: Power dissipation versus direct output current and ambient temperature

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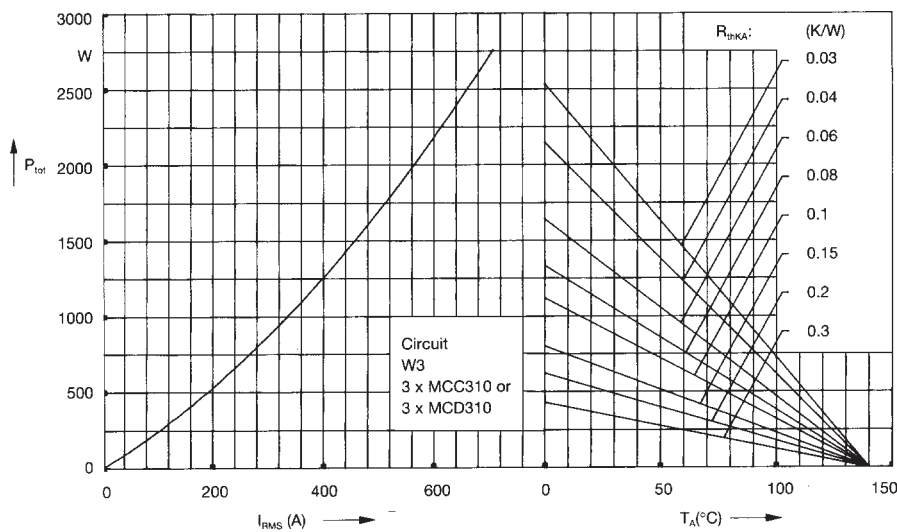


Fig. 7 Three phase AC-controller: Power dissipation versus RMS output current and ambient temperature

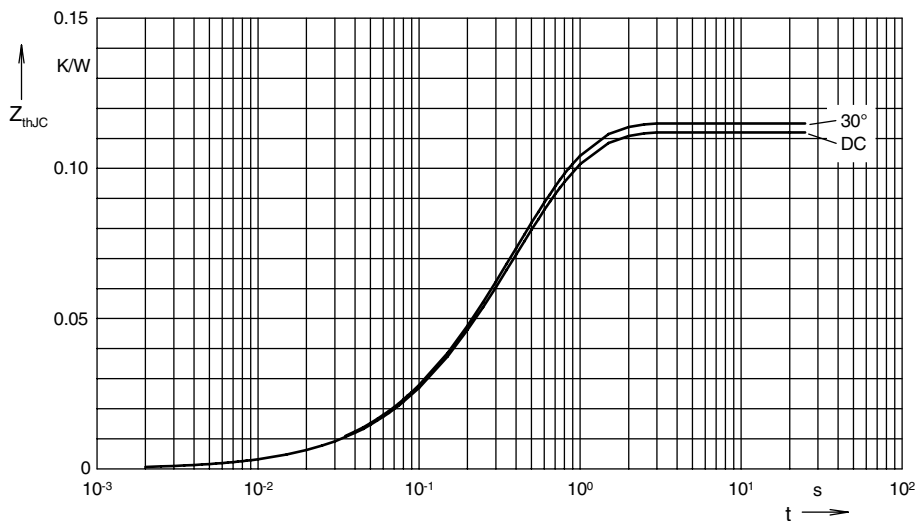


Fig. 8 Transient thermal impedance junction to case (per thyristor or diode)

R_{thJC} for various conduction angles d :

d	R_{thJC} (K/W)
DC	0.112
180°C	0.113
120°C	0.114
60°C	0.115
30°C	0.115

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.003	0.099
2	0.0143	0.168
3	0.0947	0.456

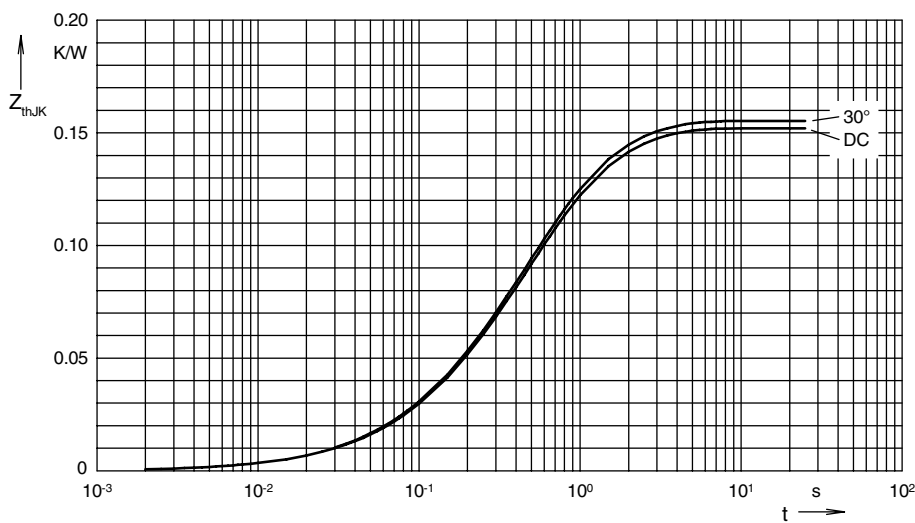


Fig. 9 Transient thermal impedance junction to heatsink (per thyristor or diode)

R_{thJK} for various conduction angles d :

d	R_{thJK} (K/W)
DC	0.152
180°C	0.154
120°C	0.154
60°C	0.155
30°C	0.155

Constants for Z_{thJK} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.003	0.099
2	0.0143	0.168
3	0.0947	0.456
4	0.04	1.36